

ATTORNEY DOCKET NO: 70031

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : MOMENI et al.
PCT No : PCT/DE99/02554
Filed : February 7, 2001
For : A METHOD....
Dated : February 23, 2001

Hon. Commissioner of Patents
and Trademarks
Washington, D.C. 20231

*G/A
2/23/01*

PRELIMINARY AMENDMENT

Prior to initial examination, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Please replace the specification originally filed, with the enclosed substitute specification. A marked up copy of the original specification is attached. Applicant states that no new matter has been added.

IN THE CLAIMS:

Please replace claims 1 to 20 without prejudice with the following new claims for initial examination on the merits:

21. A method for placing a multitude of shaped parts of solder material on a bond pad arrangement of a substrate, said bond pad arrangement comprising a multitude of bond